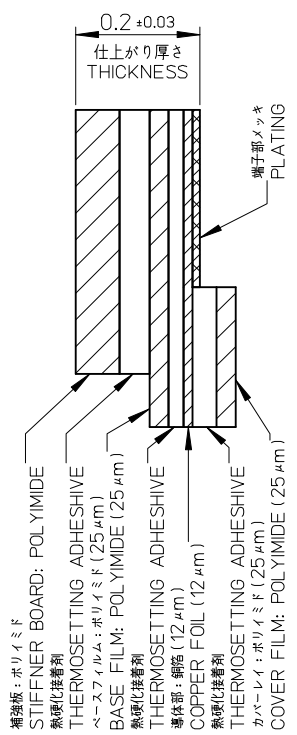


注記 NOTES

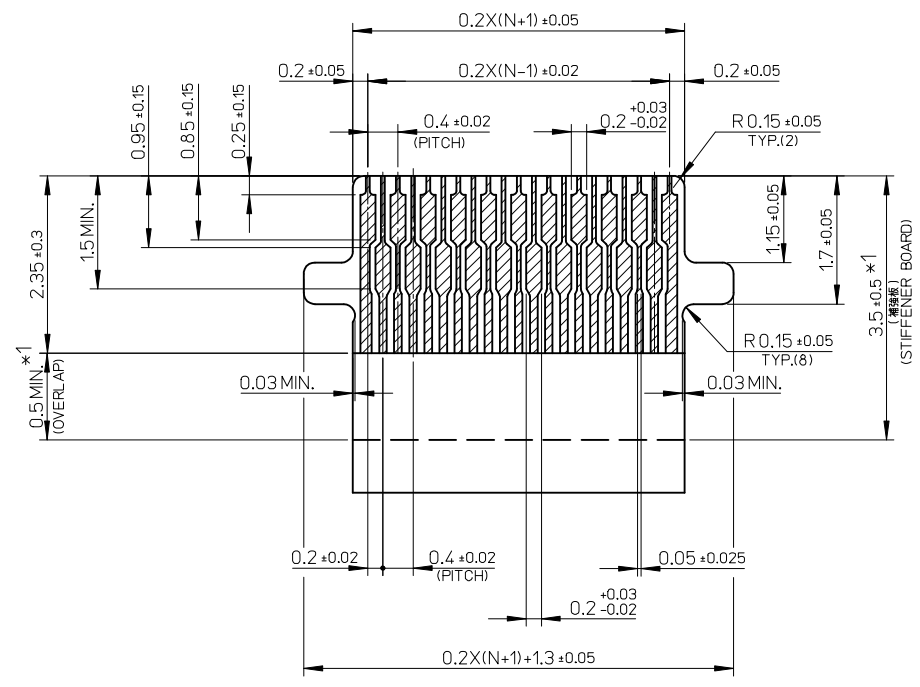
- 使用材料 MATERIALS
 ハウジング : 液晶ポリマー(LCP) ガラス充填、UL94V-0、ナチュラル(白色系)
 アクチュエータ: ポリアミド(PA) ガラス充填、UL94 HB、黒色
 奇数端子 : 銅合金、ニッケル下地、金メッキ
 偶数端子 : 銅合金、ニッケル下地、金メッキ
 補強金具 : 銅合金、ニッケル下地、金メッキ
 HOUSING : LIQUID CRYSTAL POLYMER(LCP), GLASS FILLED UL94V-0, NATURAL(WHITE)
 ACTUATOR : POLYAMIDE(PA), GLASS FILLED UL94 HB, BLACK
 ODD TERMINAL : COPPER ALLOY, Gold OVER Nickel PLATING
 EVEN TERMINAL : COPPER ALLOY, Gold OVER Nickel PLATING
 FITTING NAIL : COPPER ALLOY, Gold OVER Nickel PLATING
- 端子、補強金具のコプラナリティーは 0.1以下とする
 COPLANALITY OF SOLDER TAILS AND FITTING NAILS: 0.1MAX.
- 一般公差: ± 0.3
 GENERAL TOLERANCES: ±0.3
- ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT

15.6	16.4	17.22	16.0	17.75	503419-0810	81
13.6	14.4	15.22	14.0	15.75	503419-0710	71
12.8	13.6	14.42	13.2	14.95	503419-0670	67
E	D	C	B	A	EMBOSSED PACKAGE	極数
CONNECTIR SERIES NO. 503419-***8						CIRCUITS
オーダー番号 ODEER NO.						

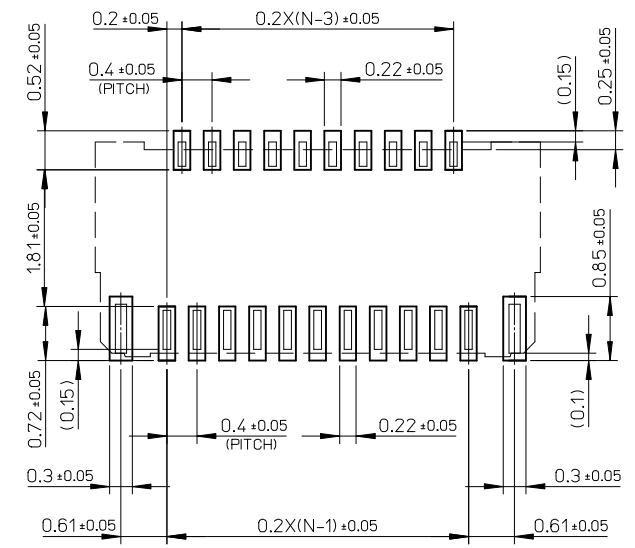
REVISED EC NO: J2015-0631 DRAWN: NKONDO 2014/11/11 CHKD: TAKAHASHI 2014/11/11 APPR: YNOGAWA 2014/11/11	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION
				MM ONLY				METRIC		
		10 UNDER ± ---		DRAWN BY NKONDO		DATE 2011/11/15		TITLE		
		10 OVER 30 UNDER ± ---		CHECKED BY HIJIMA		DATE 2011/11/15		0.2 FPC CONN E/O BTM CONTACT TYPE HGT=0.9MM		
30 OVER ± ---		APPROVED BY KMORIKAWA		DATE 2011/11/16		MATERIAL NO.		DOCUMENT NO.		
ANGULAR ±1°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		503419-***8		SD-503419-001		SHEET NO. 1 OF 2		
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



FPC構成推奨仕様
STRUCTURE OF FPC



適合するFPC推奨寸法 (参考)
APPLICABLE FPC
PATTERN DIMENSIONS(REF.)
(端子部仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)



参考基板レイアウト
RECOMMENDED PCB
PATTERN DIMENSIONS(REF.)

推奨ベスト厚 : 100μm
推奨マスク開口率 : 80%
RECOMMEND SCREEN THICKNESS : 100μm
RECOMMEND SCREEN OPEN RATIO : 80%

・FPCについて (ABOUT FPC)

抜き方向は、導体側から補強板側を推奨します
補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します
なお、接着剤の接点部への付着は導通不良の原因となりますので
染み出しがないよう、お願いします

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE

RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON
ADHEREND BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY

・FPCパターンメッキ仕様

金メッキ: 0.14μm 以上
下地ニッケルメッキ: 2~6μm
FPC PATTERN PLATING
GOLD PLATING : 0.14μm MINIMUM
NICKEL UNDER PLATING : 2~6μm

*1 補強板長さが図面通り確保できない場合は、カバーレイと
補強板のオーバーラップ寸法を 0.5mm 以上としてください
WHEN STIFFENER BOARD DIMENSION CAN NOT
SECURE AS DRAWING, PLEASE GIVE THE OVERLAP
SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM

SEE SHEET 1 OF 2	EC NO: J2015-0631	2014/11/11	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	DR/MNKND00	2014/11/11	10 UNDER	± ---	DRAWN BY	DATE	TITLE	0.2 FPC CONN E/O BTM CONTACT TYPE HGT=0.9MM molex	
	CHKD:KAKAHASHI	2014/11/11	10 OVER 30 UNDER	± ---	CHECKED BY	DATE			
	APPR:YNOGAWA	2014/11/11	30 OVER	± ---	APPROVED BY	DATE			
REV		ANGULAR	±1 °	MATERIAL NO.	DOCUMENT NO.	SHEET NO.			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		503419-***8	SD-503419-001	2 OF 2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	